### **Features**

- Low power consumption
- · Low voltage drop
- · Low temperature coefficient
- High input voltage (up to 40V)
- Output voltage accuracy: tolerance  $\pm 1.5\%$
- · Soft start function
- Over current protection
- · Over temperature protection
- Package types: 3-pin SOT89, 5-pin SOT23

### **Applications**

- Industrial/Automotive Application
- · Power Meter, Water Meter, Smart Meter
- Portable/Battery-Powered Equipment

## **General Description**

The HT73Hxx series is a set of low power consumption high voltage regulator implemented in a BCD technology, which ensures low voltage drop and low quiescent current. They allow input voltages as high as 40V. They are available with several fixed output voltages ranging from 2.1V to 5.0V.

The soft start function controls the output slew rate to prevent the overshooting phenomenon when power on. The enable pin, CE, accepts CMOS level as logic input. When CE goes low, a fast discharging path pulls output voltage low a via  $300\Omega$  resistor. The internally output over current protection prevents the HT73Hxx from being burned even if the output node shorts to ground. The over temperature protection ensures that the junction temperature will not exceed  $150^{\circ}\text{C}$ . The soft start function inhibits the output overshooting when power on.

#### **Selection Table**

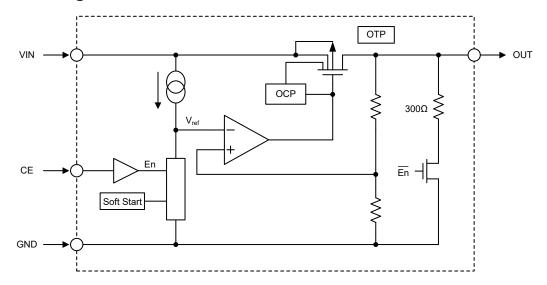
Part No.	Output Voltage	Package	Marking	
HT73H21	2.1V			
HT73H23	2.3V			
HT73H25	2.5V			
HT73H27	2.7V			
HT73H30	3.0V	SOT89	HT73Hxx (for SOT89)	
HT73H33	3.3V	SOT23-5	SOT23-5 3Hxx (for SOT23-5)	3Hxx (for SOT23-5)
HT73H36	3.6V			
HT73H40	4.0V			
HT73H44	4.4V			
HT73H50	5.0V			

Note: "xx" stands for output voltages.

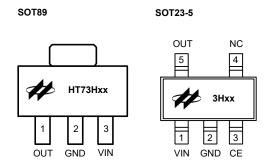
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# **Block Diagram**



# **Pin Assignment**



# **Pin Descriptions**

Pin No.		Pin Name	Pin Description	
SOT89	SOT23-5	Pili Naille	Pili Description	
3	1	VIN	Input pin	
2	2	GND	Ground pin	
1	5	OUT	Output pin	
_	3	CE	Chip enable pin, high enable	
_	4	NC	No connection	

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# **Absolute Maximum Ratings**

Parameter	Value	Unit	
V <sub>IN</sub>		-0.3 to +48	V
Vce		-0.3 to (V <sub>IN</sub> +0.3)	V
Operating Temperature Range, Ta		-40 to +85	°C
Maximum Junction Temperature, T <sub>J(MAX)</sub>		+150	°C
Storage Temperature Range	-60 to +150	°C	
TSD Suggestibility	Human Body Model	±5000	V
ESD Susceptibility	Machine Model	±400	V
Junction-to-Ambient Thermal Resistance, θ <sub>JA</sub> SOT89  SOT23-5		200	°C/W
		500	°C/W
Power Dissipation D	SOT89	0.625	W
Power Dissipation, P <sub>D</sub>	SOT23-5	0.25	W

Note:  $P_D$  is measured at Ta=25°C.

# **Recommended Operating Range**

Parameter	Value	Unit
$V_{IN}$	(V <sub>OUT</sub> +2) to 40	V
V <sub>CE</sub>	0 to V <sub>IN</sub>	V

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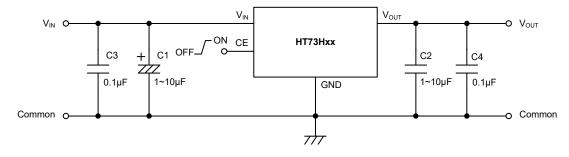


## **Electrical Characteristics**

 $V_{IN}=V_{OUT}+2V$ ,  $V_{CE}=V_{IN}$ ,  $Ta=25^{\circ}C$  and  $C_{IN}=C_{OUT}=1\mu F$ , unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>IN</sub>	Input Voltage	_	_	_	40	V
V <sub>OUT</sub>	Output Voltage Range	_	2.1	_	5.0	V
Vo	Output Voltage Accuracy	I <sub>OUT</sub> =10mA	-1.5	_	1.5	%
	Output Current	V <sub>OUT</sub> =2.1V to 3.0V	180	_	_	mA
lout	Output Current	V <sub>OUT</sub> =3.3V to 5.0V		_	_	IIIA
$\Delta V_{OUT}$	Load Regulation	1mA≤I <sub>OUT</sub> ≤100mA	_	45	90	mV
\/	Drangut Valtage	I <sub>OUT</sub> =1mA, V <sub>OUT</sub> Change=2% (Note)	_	5	15	mV
V <sub>DIF</sub>	Dropout Voltage	I <sub>OUT</sub> =30mA, V <sub>OUT</sub> Change=2% (Note)	_	80	300	mV
	Quiescent Current	I <sub>OUT</sub> =0mA	_	2.5	4.0	μA
Iss	Quiescent Current	V <sub>CE</sub> =2.2V, V <sub>IN</sub> =40V, I <sub>OUT</sub> =0mA	_	3.0	5.0	μΑ
I <sub>SHD</sub>	Shutdown Current	V <sub>CE</sub> =0V	_	0.1	1.0	μA
$\frac{\Delta V_{\text{OUT}}}{\Delta V_{\text{IN}} \times \Delta V_{\text{OUT}}}$	Line Regulation	(V <sub>OUT</sub> +1V)≤V <sub>IN</sub> ≤40V, I <sub>OUT</sub> =1mA	_	0.1	0.2	%/V
$\frac{\Delta V_{\text{OUT}}}{\Delta \text{Ta} \times \Delta V_{\text{OUT}}}$	Temperature Coefficient	I <sub>OUT</sub> =10mA, -40°C <ta<85°c< td=""><td>_</td><td>±100</td><td>_</td><td>ppm/°C</td></ta<85°c<>	_	±100	_	ppm/°C
I <sub>OCP1</sub>	OCP1 Current Threshold	V <sub>IN</sub> =24V	350	_	_	mA
I <sub>OCP2</sub>	OCP2 Current Threshold	V <sub>IN</sub> =24V, force V <sub>OUT</sub> =0V	_	300	_	mA
V <sub>OCP_TH</sub>	OCP1/OCP2 Current Threshold	Observe at V <sub>OUT</sub> terminal	_	0.7	_	V
T <sub>SHD</sub>	Shutdown Temperature	_	_	150	_	°C
T <sub>REC</sub>	Recovery Temperature	_	_	120	_	°C
V <sub>IH</sub>	Enable High Threshold	CE pin, (V <sub>OUT</sub> +1V)≤V <sub>IN</sub> ≤40V	2	_	_	V
V <sub>IL</sub>	Enable Low Threshold	CE pin, (V <sub>OUT</sub> +1V)≤V <sub>IN</sub> ≤40V	_	_	0.6	V
R <sub>DIS</sub>	Discharge Resistor	V <sub>IN</sub> =24V, CE=0V, measure at V <sub>OUT</sub>	_	300	_	Ω
PSRR	Power Supply Rejection Ratio	V <sub>IN</sub> =24V, V <sub>OUT</sub> =5V, I <sub>OUT</sub> =10mA, f=1kHz	_	60	_	dB
Noise	Output Voltage Noise	V <sub>OUT</sub> =5V, I <sub>OUT</sub> =10mA, BW=10Hz~100kHz	_	75	_	μV <sub>RMS</sub>

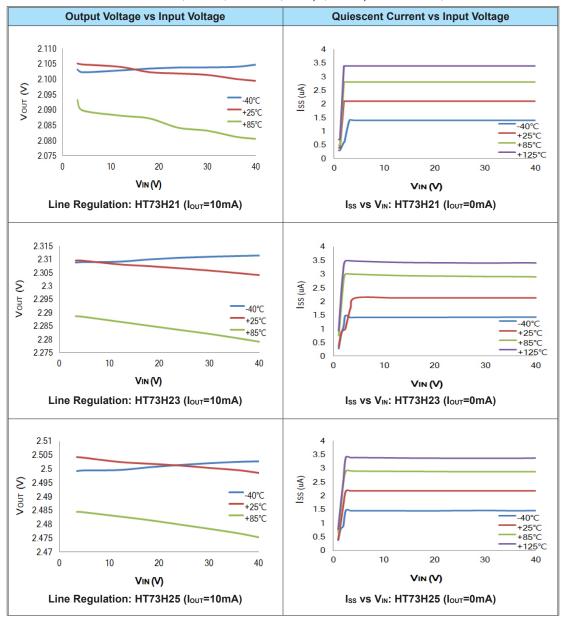
Note: Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at  $V_{IN}=V_{OUT}+2V$  with a fixed load.



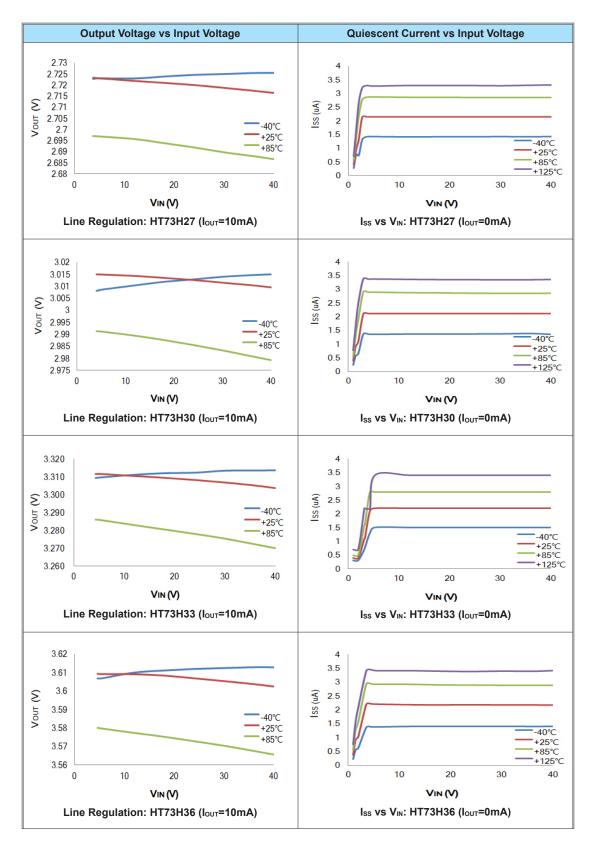


## **Typical Performance Characteristic**

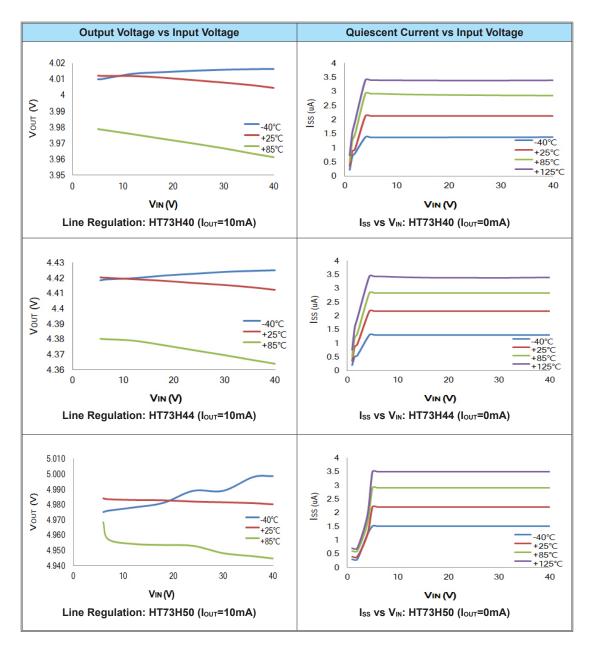
Test Condition:  $V_{\text{IN}} = V_{\text{OUT}} + 2V$ ,  $V_{\text{CE}} = V_{\text{IN}}$ ,  $I_{\text{OUT}} = 10\text{mA}$ ,  $C_{\text{IN}} = 1\mu\text{F}$ ,  $C_{\text{OUT}} = 1\mu\text{F}$  and  $Ta = 25^{\circ}\text{C}$ , unless otherwise noted.





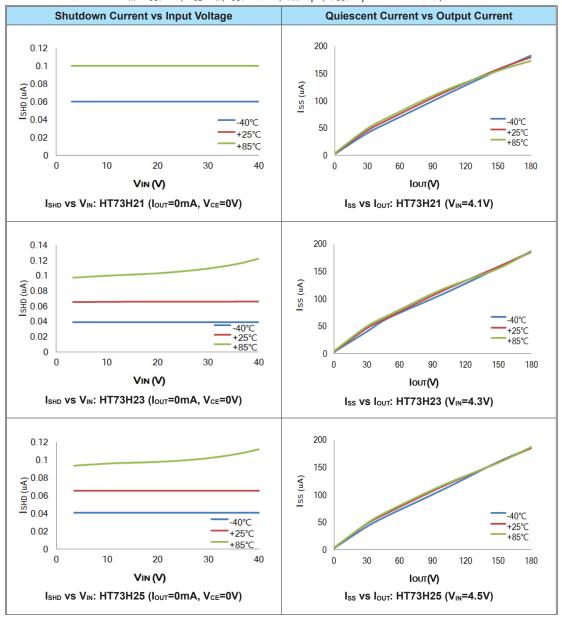




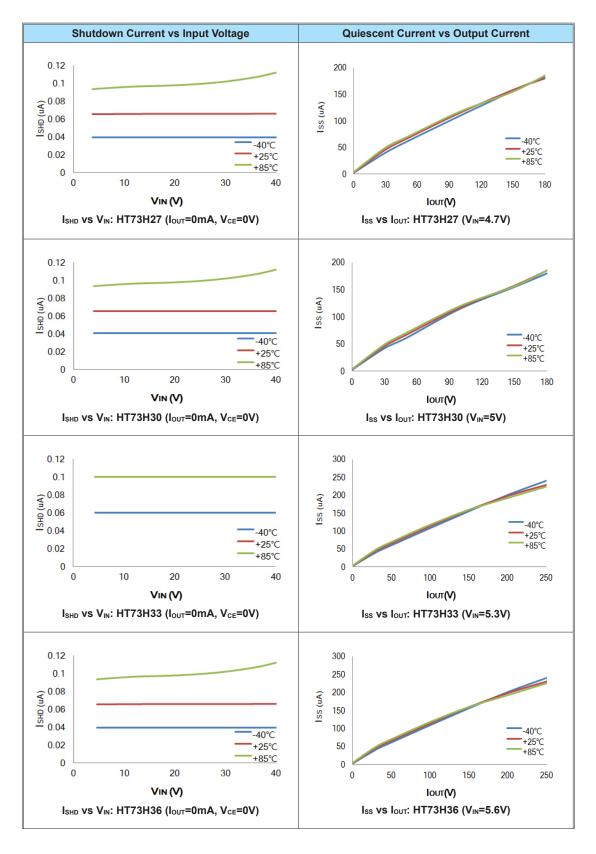




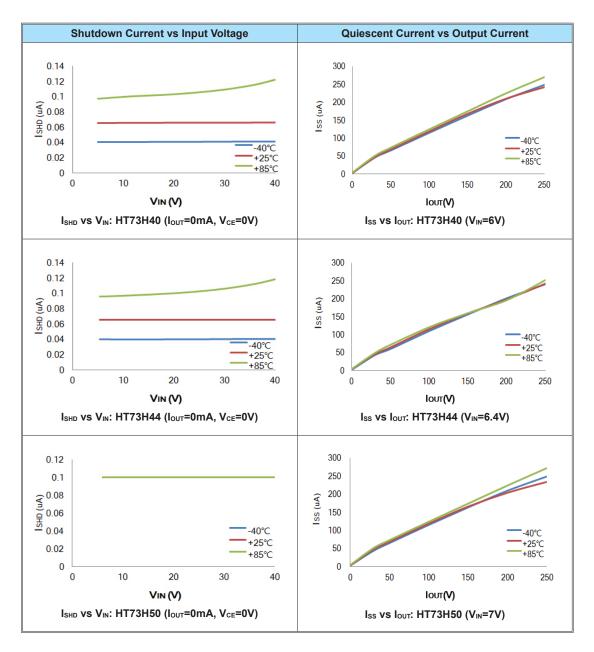
Test Condition:  $V_{IN}=V_{OUT}+2V$ ,  $V_{CE}=V_{IN}$ ,  $I_{OUT}=10mA$ ,  $C_{IN}=1\mu F$ ,  $C_{OUT}=1\mu F$  and  $Ta=25^{\circ}C$ , unless otherwise noted.



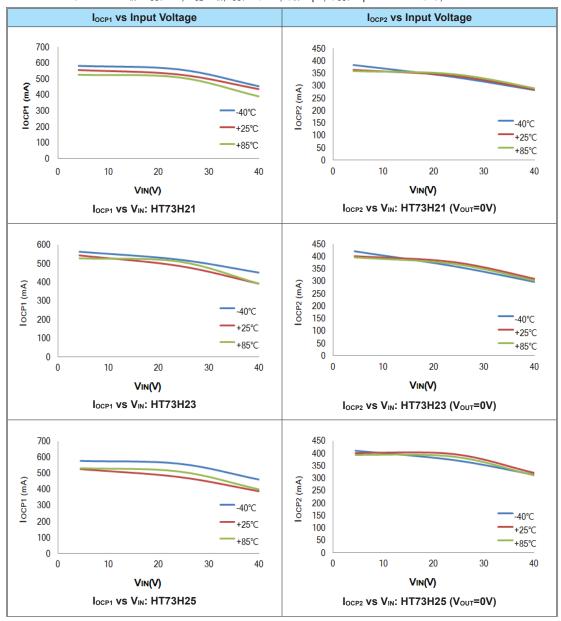




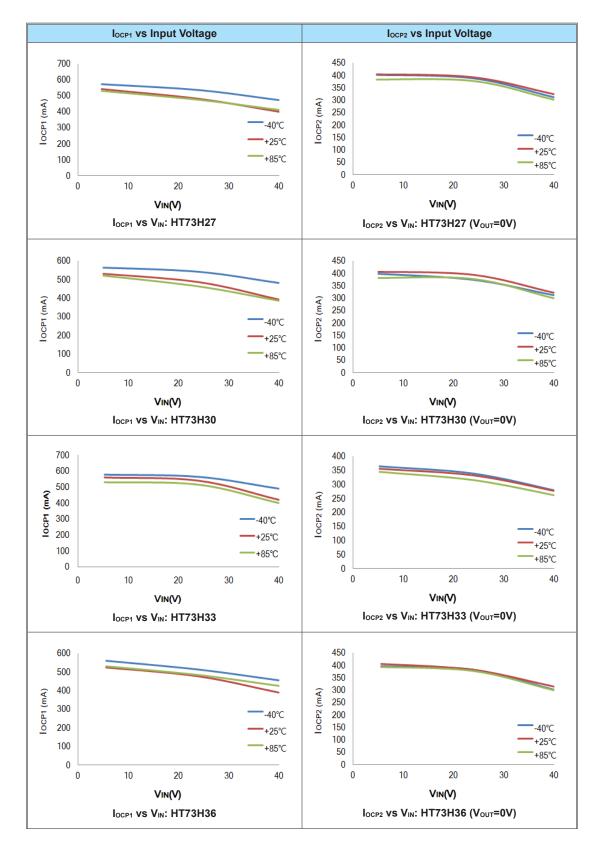




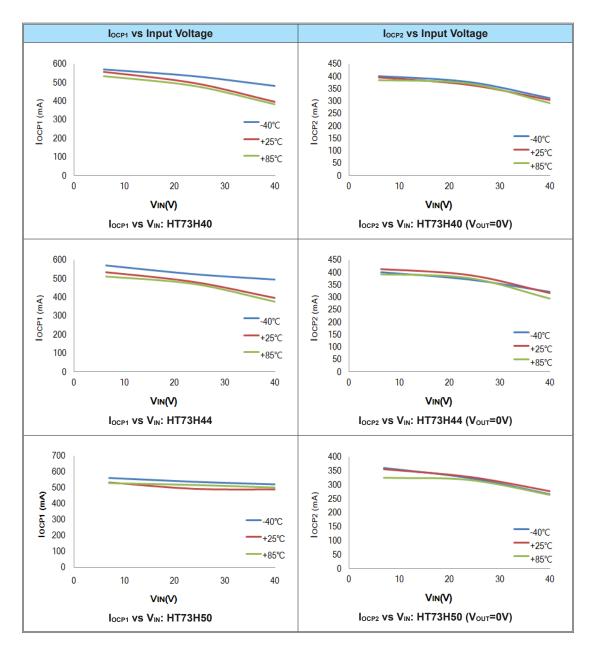






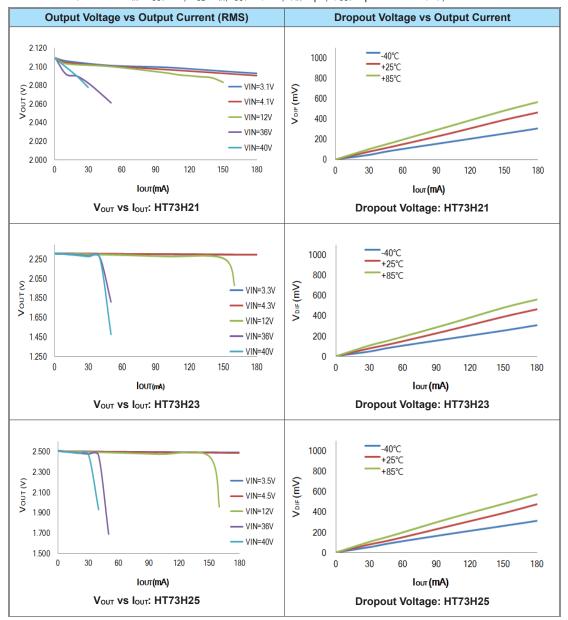




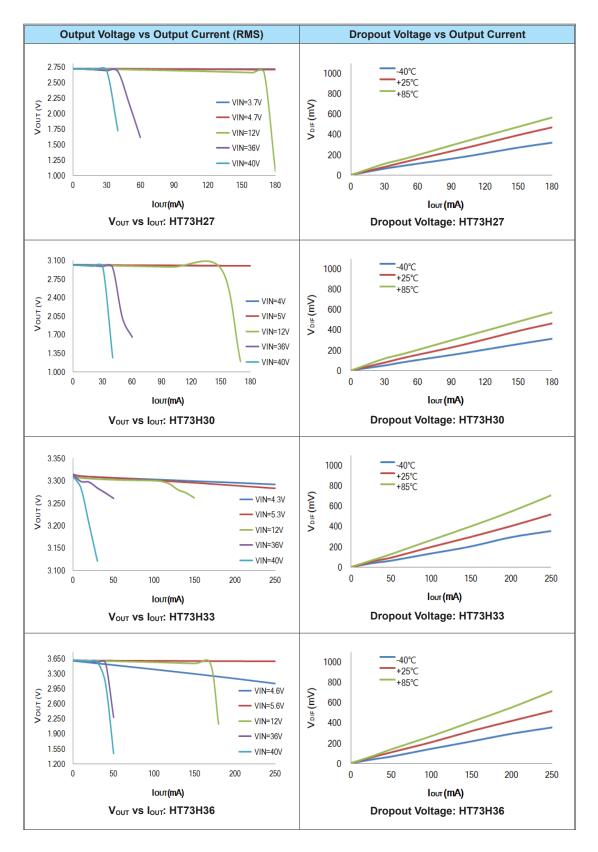




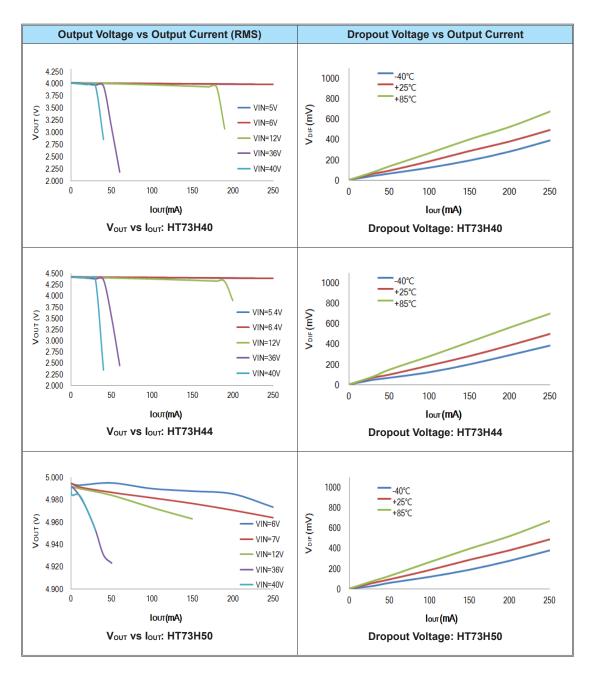
 $Test\ Condition:\ V_{IN}=V_{OUT}+2V,\ V_{CE}=V_{IN},\ I_{OUT}=10mA,\ C_{IN}=1\mu F,\ C_{OUT}=1\mu F\ and\ Ta=25^{\circ}C,\ unless\ otherwise\ noted.$ 



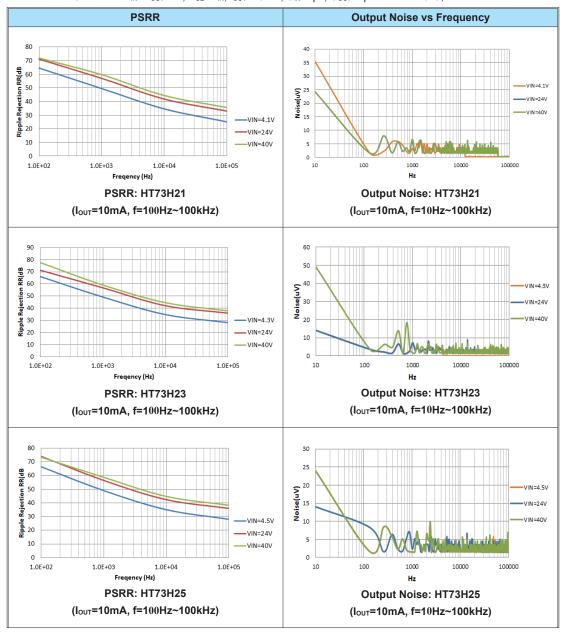




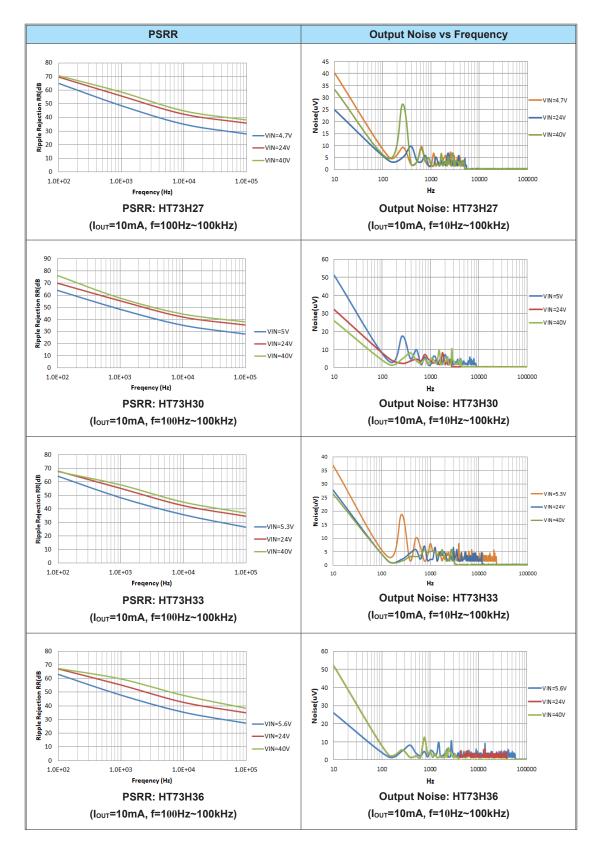




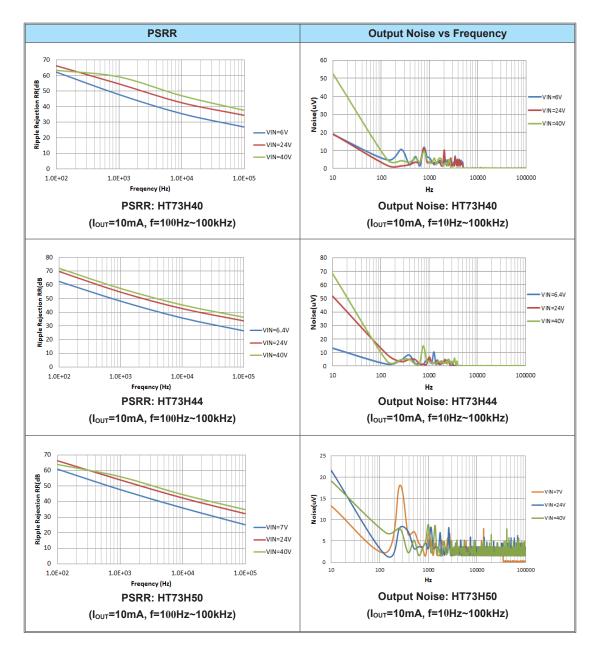




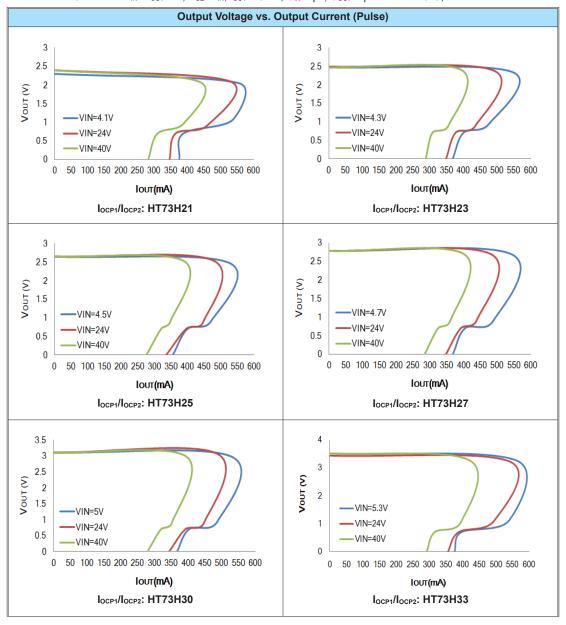




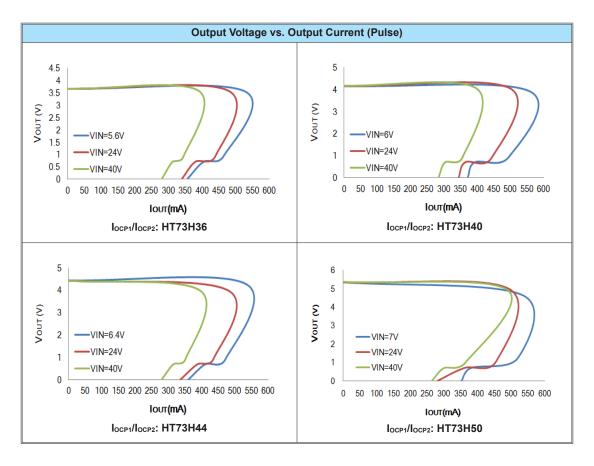




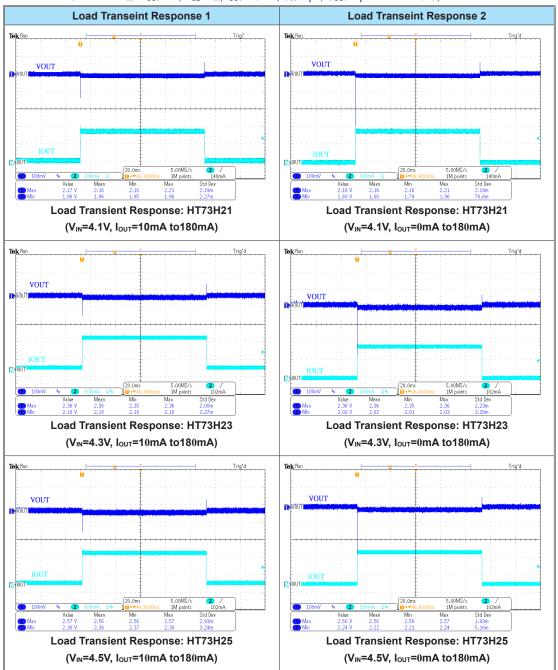




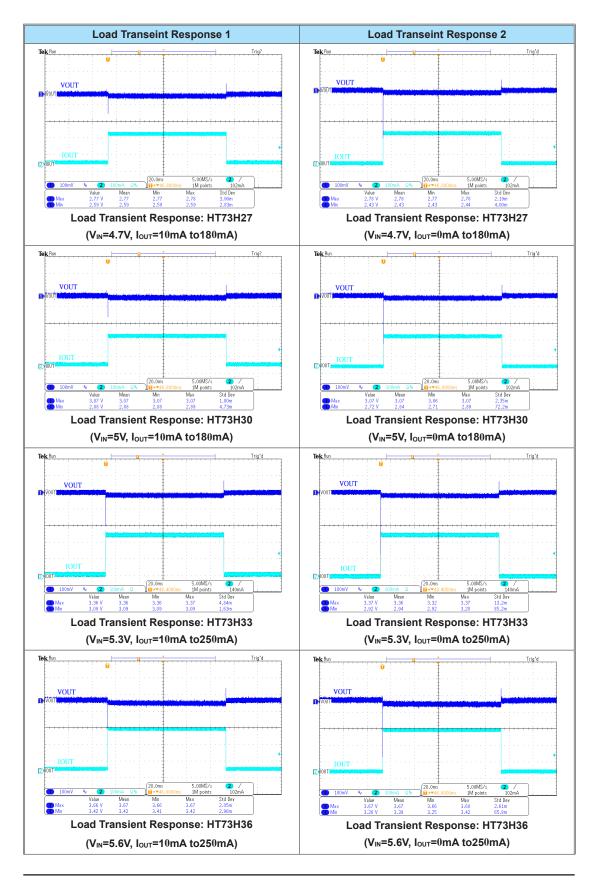




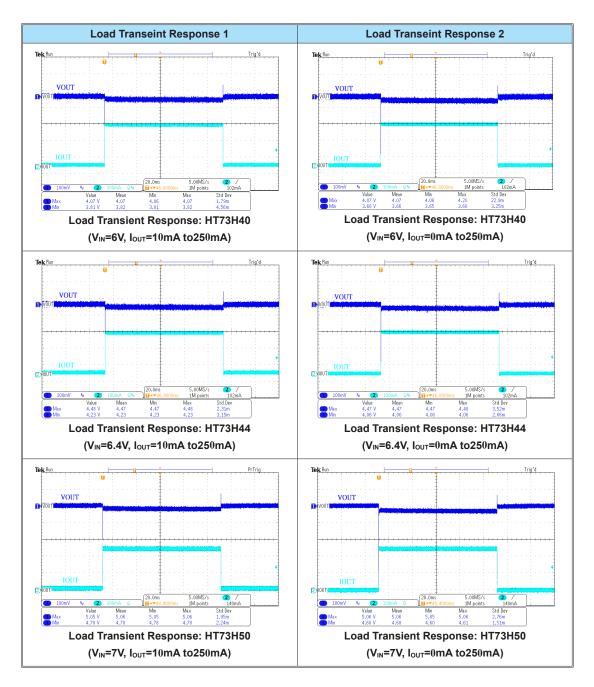






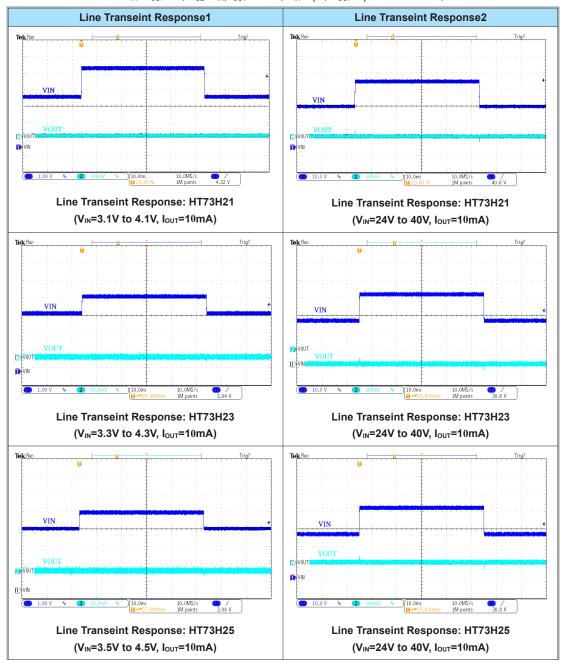




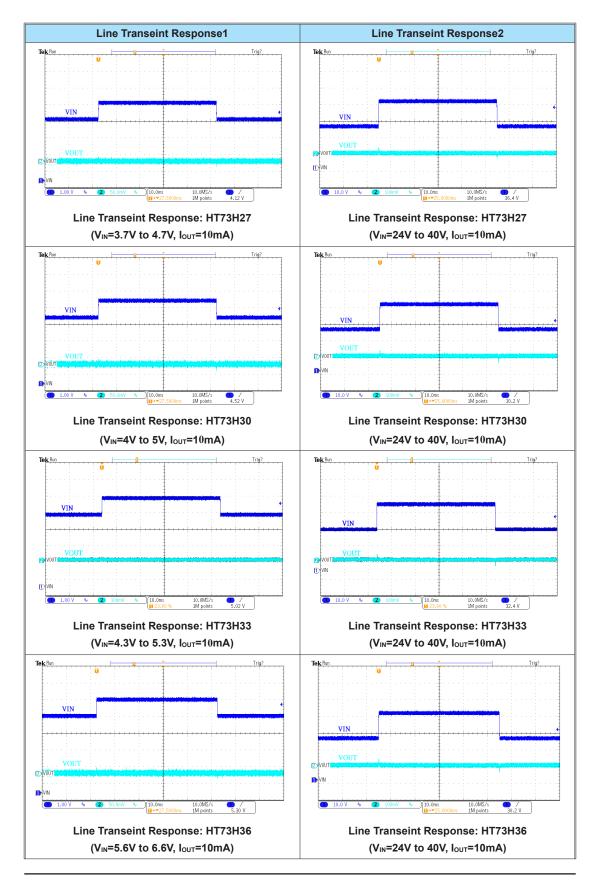




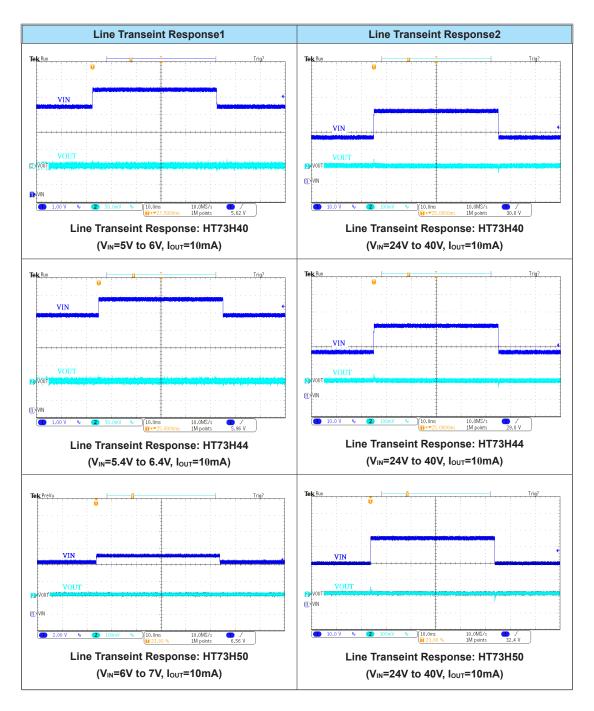
Test Condition:  $V_{IN}=V_{OUT}+2V$ ,  $V_{CE}=V_{IN}$ ,  $I_{OUT}=10mA$ ,  $C_{IN}=1\mu F$ ,  $C_{OUT}=1\mu F$  and  $Ta=25^{\circ}C$ , unless otherwise noted.





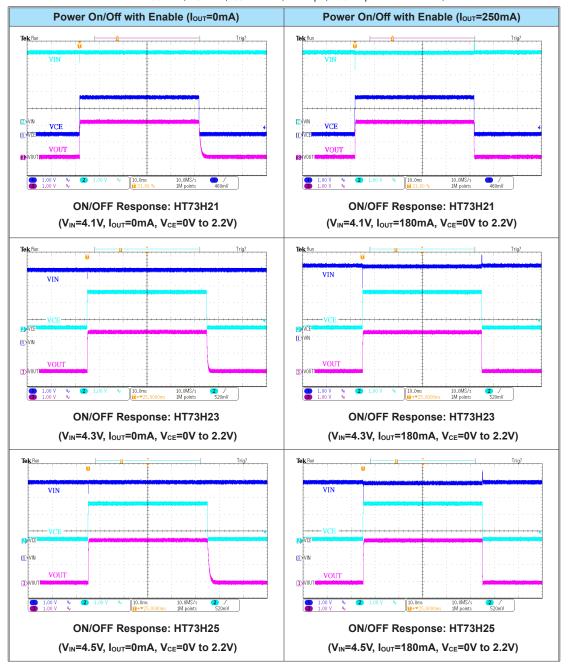




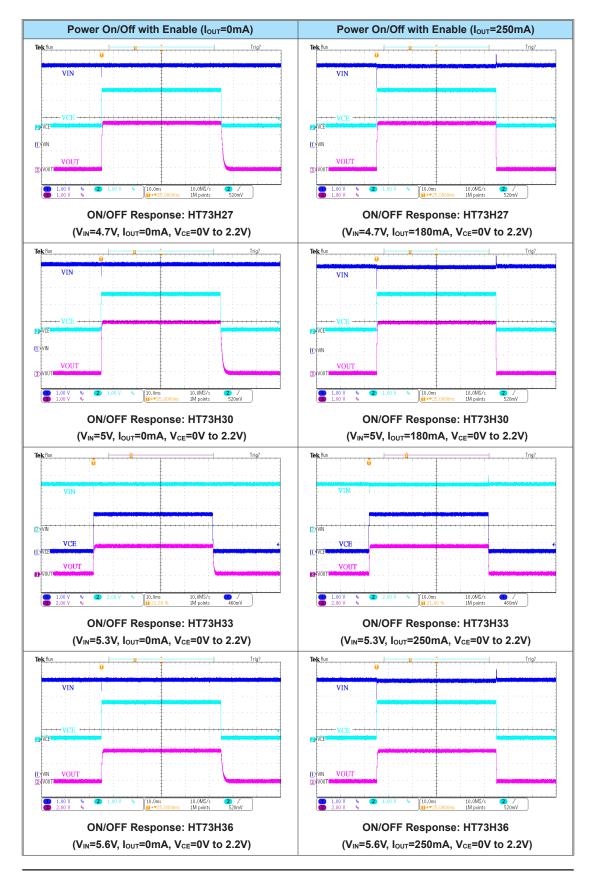




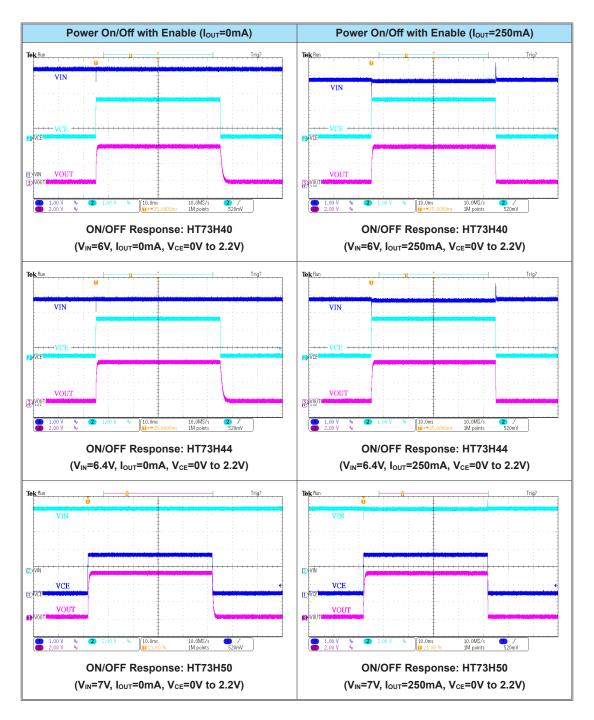
Test Condition:  $V_{IN}=V_{OUT}+2V$ ,  $V_{CE}=V_{IN}$ ,  $I_{OUT}=10mA$ ,  $C_{IN}=1\mu F$ ,  $C_{OUT}=1\mu F$  and  $Ta=25^{\circ}C$ , unless otherwise noted.



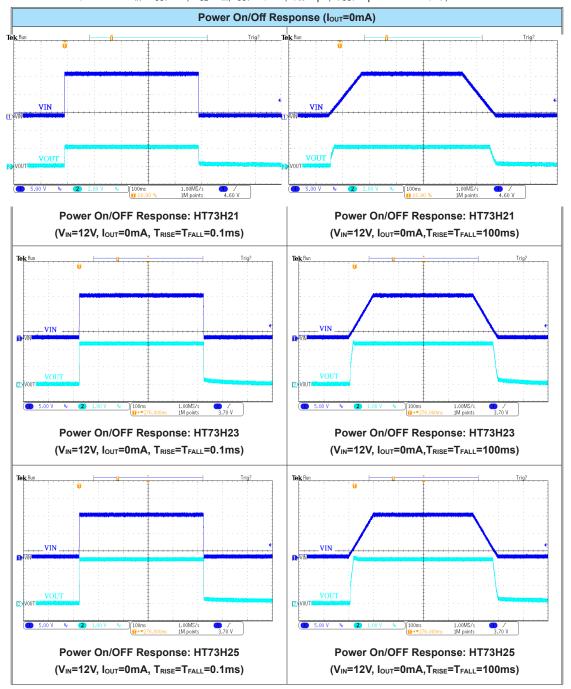




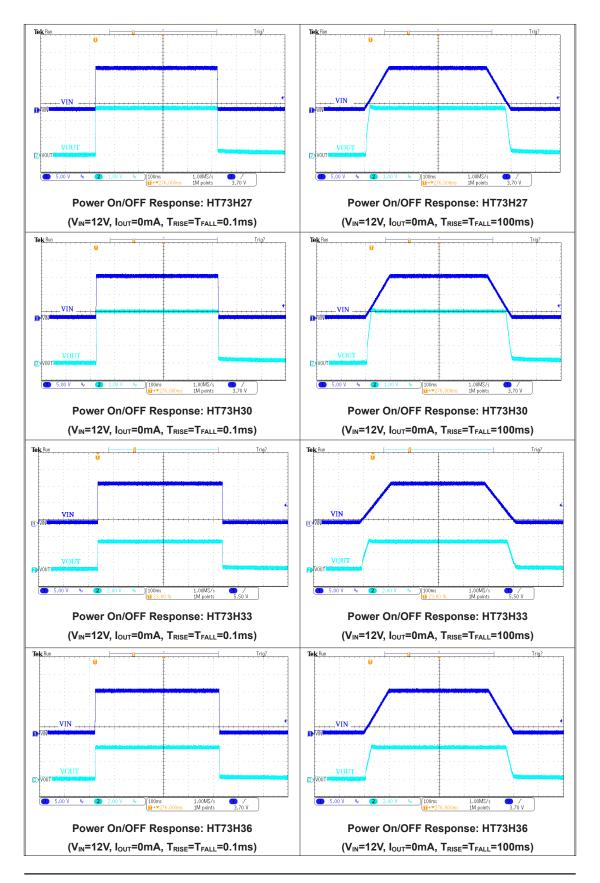




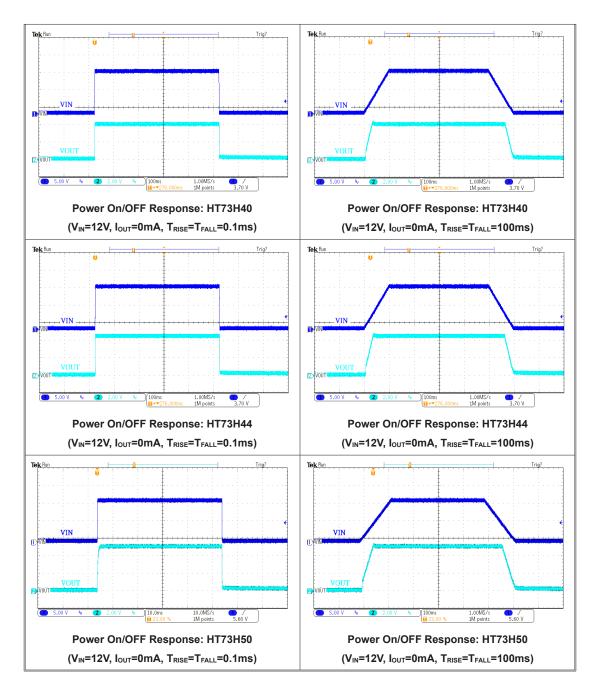






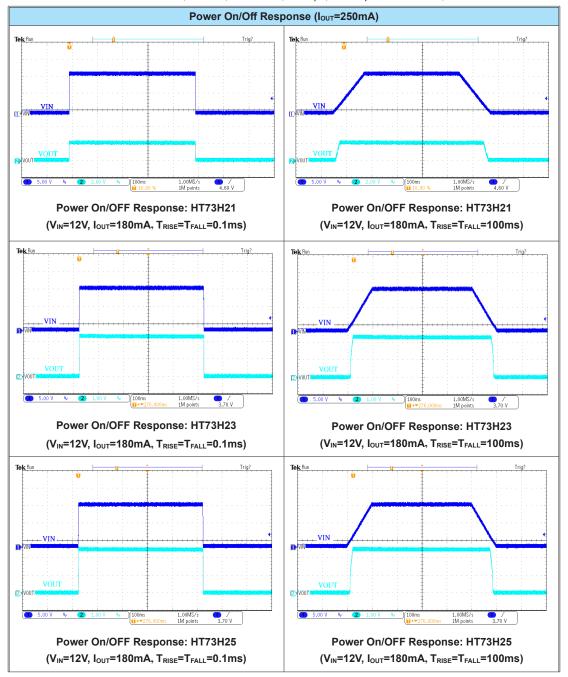




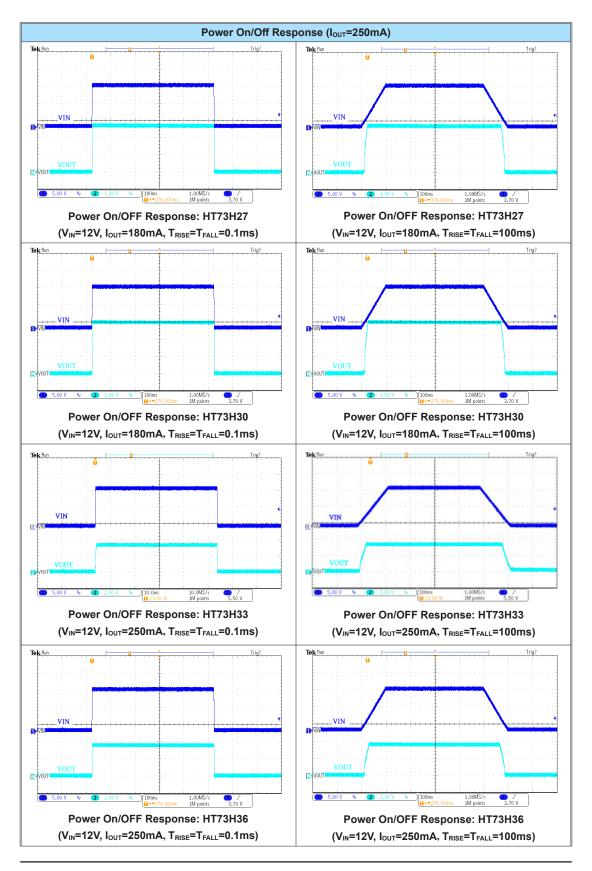




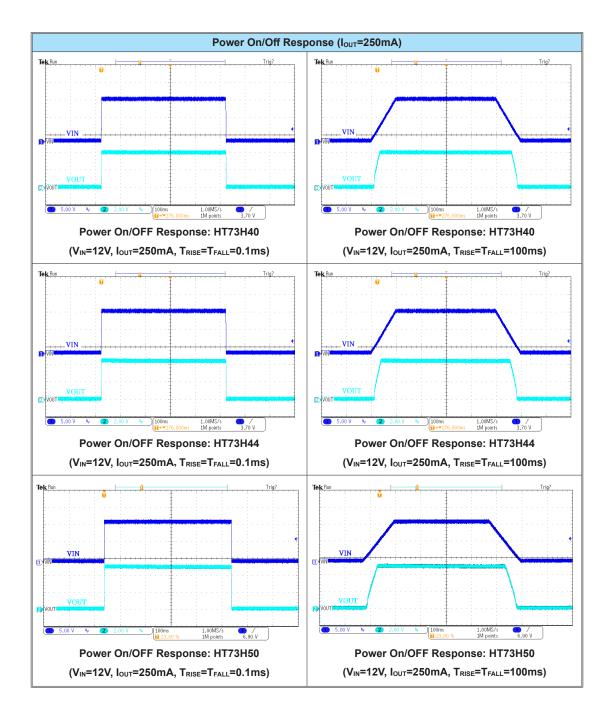
Test Condition:  $V_{IN}=V_{OUT}+2V$ ,  $V_{CE}=V_{IN}$ ,  $I_{OUT}=10mA$ ,  $C_{IN}=1\mu F$ ,  $C_{OUT}=1\mu F$  and  $Ta=25^{\circ}C$ , unless otherwise noted.











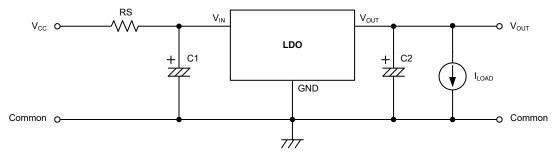


### **Application Information**

When using the HT73Hxx regulators, it is important that the following application points are noted if correct operation is to be achieved.

#### **Power-on Considerations**

In order to suppress the output overshooting phenomenon, the rising time of input supply is suggested greater than 1ms. Adding an input resistor RS which is acting like a low-pass filter, it can slow down the rising time of the input supply in the  $V_{\rm IN}$  terminal, as shown below.



The maximum RS is limited by ILOAD(MAX) and VDROPOUT. It be calculated by the following equation.

$$RS \!\! \leq \!\! \frac{V_{\text{CC}} \!\! - \! V_{\text{DROPOUT}}}{I_{\text{LOAD(MAX)}}}$$

Once the RS value is selected, the minimum value of C1 can be calculated by the following equation:

$$C1 \ge \frac{1 \text{ms}}{2.2 \text{RS}}$$

#### **OCP and OTP Protections**

The HT73Hxx implements the over current protection and over junction temperature protection to prevent IC damage even if the output is shorted to ground. When the output is shorted to ground, the output current will be clamped to  $I_{OCP2}$  and the junction temperature will rise. Once the junction temperature exceeds 150°C, the HT73Hxx will shut down the power component to prevent thermal damage. The protection will be released when the junction temperature falls to 120°C.

There are 2 levels of over current protection threshold existing in the HT73Hxx. Once the output voltage is greater than 0.7V, the OCP limit current is set to  $I_{\text{OCP1}}$ . Otherwise then the output voltage is less than 0.7V, the OCP current folds back to  $I_{\text{OCP2}}$  in order to slow down the junction temperature rises even if the output terminal is shorted to ground.

#### **Fast Output Discharging Function**

When CE='L', the output voltage will be fast discharged to 0V via an internal  $300\Omega$  resistor. This discharging path doesn't use protections such as OCP/OTP.

### Input Capacitor C<sub>IN</sub> Consideration

It is recommended that the input capacitor should be at least  $1\mu F$  and be ceramic type for better temperature coefficient and lower ESR (Equivalent Series Resistance).

### **Output Capacitor Cout Considerations**

The output capacitance plays an important role in keeping the output voltage stable. For the ceramic type capacitor, the capacitance should be at least  $1\mu F$ . For the E-cap type capacitor, the capacitance should be at least  $2.2\mu F$ .



#### **Thermal Considerations**

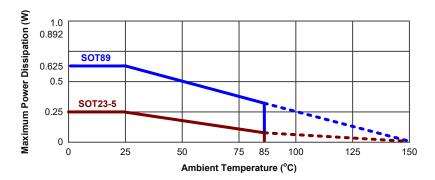
The maximum power dissipation depends on the thermal resistance of the package, the PCB layout, the rate of the surrounding airflow and the difference between the junction and ambient temperature. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - Ta) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature, Ta is the ambient temperature and  $\theta_{JA}$  is the junction-to-ambient thermal resistance of the IC package in degrees per watt. The following table shows the  $\theta_{JA}$  values for various package types.

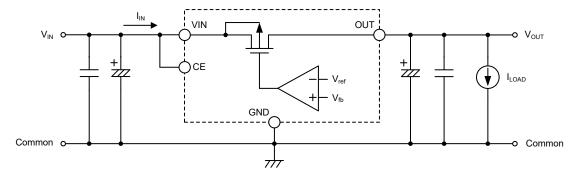
Package Type	θ <sub>JA</sub> (°C/W)
SOT89	200 °C/W
SOT23-5	500 °C/W

For maximum operating rating conditions, the maximum junction temperature is 150°C. However, it is recommended that the maximum junction temperature does not exceed 125°C during normal operation to maintain an adequate margin for device reliability. The derating curves of different packages for maximum power dissipation are as follows:



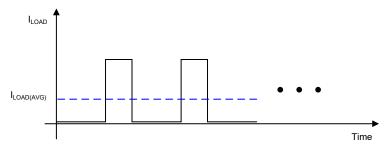
#### **Power Dissipation Calculation**

In order to keep the device within its operating limits and to maintain a regulated output voltage, the power dissipation of the device, given by  $P_D$ , must not exceed the Maximum Power Dissipation, given by  $P_D(MAX)$ . Therefore,  $P_D \leq P_{D(MAX)}$ . From the diagram it can be seen that almost all of this power is generated across the pass transistor which is acting like a variable resistor in series with the load to keep the output voltage constant. This generated power which will appear as heat, must never allow the device to exceed its maximum junction temperature.





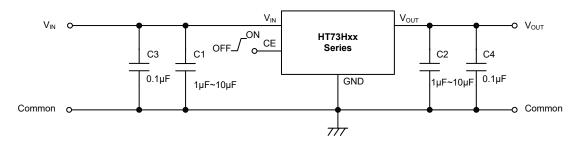
In practical applications the regulator may be called upon to provide both steady state and transient currents due to the transient nature of the load. Although the device may be working well within its limits with its steady state current, care must be taken with transient loads which may cause the current to rise close to its maximum current value. Care must be taken with transient loads and currents as this will result in device junction temperature rises which must not exceed the maximum junction temperature. With both steady state and transient currents, the important current to consider is the average or more precisely the RMS current which is the value of current that will appear as heat generated in the device. The following diagram shows how the average current relates to the transient currents.



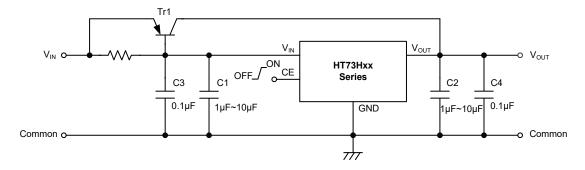
As the quiescent current of the device is very small it can generally be ignored and as a result the input current can be assumed to be equal to the output current. Therefore the power dissipation of the device,  $P_D$ , can be calculated as the voltage drop across the input and output multiplied by the current, given by the equation,  $P_D=(V_{IN}-V_{OUT})\times I_{IN}$ . As the input current is also equal to the load current the power dissipation  $P_D=(V_{IN}-V_{OUT})\times I_{LOAD}$ . However, with transient load currents,  $P_D=(V_{IN}-V_{OUT})\times I_{LOAD(AVG)}$  as shown in the figure.

### **Application Circuits**

#### **Basic Circuits**

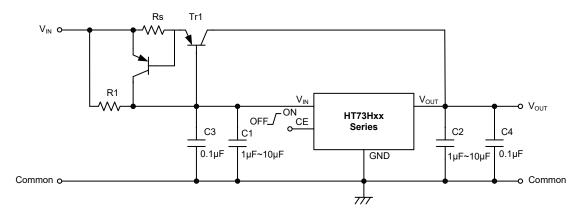


### **High Output Current Positive Voltage Regulator**



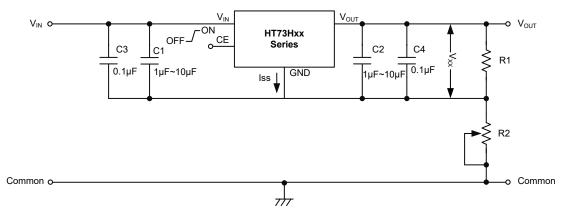


## **Short-Circuit Protection by Tr1**

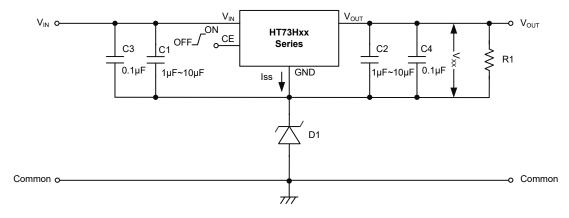


## **Increasing Output Voltage Circuits**

 $V_{OUT} = V_{XX} \times (1+R2/R1) + I_{SS} \times R2$ 

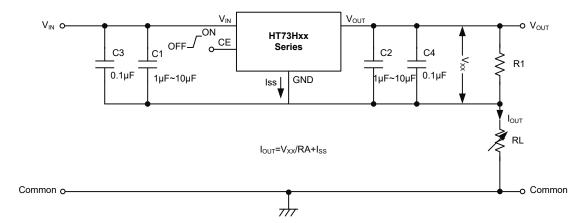


### $V_{OUT} = V_{XX} + V_{D1}$

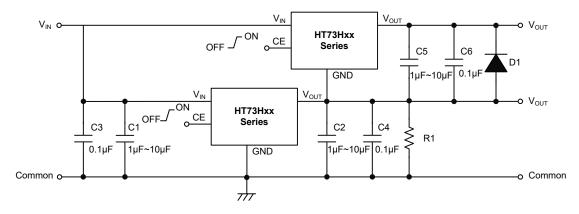




## **Constant Current Regulator**



## **Dual Supply**





## **Package Information**

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the <u>Holtek website</u> for the latest version of the <u>package information</u>.

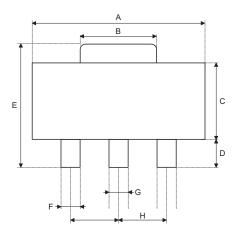
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

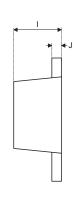
- Further Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- Packing Meterials Information
- Carton information

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## 3-pin SOT89 Outline Dimensions



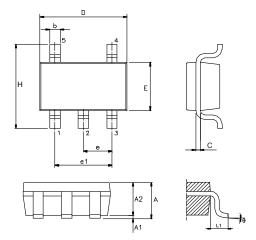


Cymphol	Dimensions in inch			
Symbol	Min.	Nom.	Max.	
Α	0.173	_	0.185	
В	0.053	_	0.072	
С	0.090	_	0.106	
D	0.031	_	0.047	
E	0.155	_	0.173	
F	0.014	_	0.019	
G	0.017	_	0.022	
Н	_	0.059 BSC	_	
I	0.055	_	0.063	
J	0.014	_	0.017	

Symbol	Dimensions in mm			
Symbol	Min.	Nom.	Max.	
A	4.40	_	4.70	
В	1.35	_	1.83	
С	2.29	_	2.70	
D	0.80	_	1.20	
E	3.94	_	4.40	
F	0.36	_	0.48	
G	0.44	_	0.56	
Н	_	1.50 BSC	_	
I	1.40	_	1.60	
J	0.35	_	0.44	



## 5-pin SOT23 Outline Dimensions



Cumbal		Dimensions in inch			
Symbol	Min.	Nom.	Max.		
А	_	_	0.057		
A1	_	_	0.006		
A2	0.035	0.045	0.051		
b	0.012	_	0.020		
С	0.003	_	0.009		
D	_	0.114 BSC	_		
Е	_	0.063 BSC	_		
е	_	0.037 BSC	_		
e1	_	0.075 BSC	_		
Н	_	0.110 BSC	_		
L1	_	0.024 BSC	_		
θ	0°	_	8°		

Cumbal	Dimensions in mm			
Symbol	Min.	Nom.	Max.	
A	_	_	1.45	
A1	_	_	0.15	
A2	0.90	1.15	1.30	
b	0.30	_	0.50	
С	0.08	_	0.22	
D	_	2.90 BSC	_	
E	_	1.60 BSC	_	
е	_	0.95 BSC	_	
e1	_	1.90 BSC	_	
Н	_	2.80 BSC	_	
L1	_	0.60 BSC	_	
θ	0°	_	8°	

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